



Intel® Desktop Board DH61SA

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Specifications

Essentials	
Status	End of Interactive Support
Launch Date	Q3'11
Board Form Factor	Micro ATX
Socket	LGA1155
Extended Life Program (XLP)	No
Embedded Options Available	No
TDP	95 W
Recommended Customer Price	N/A
Datasheet	Link
Description	Link

Memory Specifications	
Max Memory Size (dependent on memory type)	8 GB
Memory Types	DDR3 800/1066/1333
Max # of Memory Channels	2
Max # of DIMMs	2

Graphics Specifications	
Graphics Output	VGA
Discrete Graphics	None
Requires a Processor with Intel Graphics Technology	Yes

Expansion Options	
PCI Support	1
Max # of PCI Express Lanes	1
PCIe x1 Gen 2.x	1
PCIe x4 Gen 2.x	0
PCIe x8 Gen 2.x	0
PCIe x16 Gen 2.x	0
PCIe x1 Gen 1.x	0
PCIe x4 Gen 1.x	0
PCIe x8 Gen 1.x	0
PCIe x16 Gen 1.x	0

I/O Specifications	
USB Revision	2
# of USB Ports	6
USB 2.0 Configuration (External + Internal)	4,2
USB 3.0 Configuration (External + Internal)	0
Total # of SATA Ports	2
Max # of SATA 6.0 Gb/s Ports	0

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PCN/MDDS Information

917938: [PCN](#)

917939: [PCN](#)

# of eSATA Ports	0
RAID Configuration	N/A
# of PATA Ports	0
# of Parallel Ports	1
Parallel Port via Internal Header	No
# of Serial Ports	1
Serial Port via Internal Header	Yes
Audio (back channel + front channel)	6,2
Integrated LAN	10/100/1000
# of PS2 Ports	1
- Package Specifications	
Low Halogen Options Available	See MDDS

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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